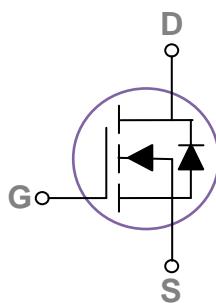
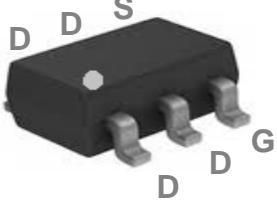


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-6 Pin Configuration



BVDSS	RDS(ON)	ID
30V	24mΩ	6.5A

Features

- 30V, 6.5A, $RDS(ON) = 24m\Omega$ @ $VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ C$)	6.5	A
	Drain Current – Continuous ($T_c=100^\circ C$)	4.1	A
I_{DM}	Drain Current – Pulsed ¹	26	A
EAS	Single Pulse Avalanche Energy ²	32	mJ
IAS	Single Pulse Avalanche Current ²	8	A
P_D	Power Dissipation ($T_c=25^\circ C$)	1.56	W
	Power Dissipation – Derate above $25^\circ C$	0.012	W/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.04	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}(\text{S})}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=10\text{V}$, $I_D=6\text{A}$	---	19	24	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=4\text{A}$	---	25	34	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
			---	-4	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=4\text{A}$	---	6.5	---	S

Dynamic and switching Characteristics

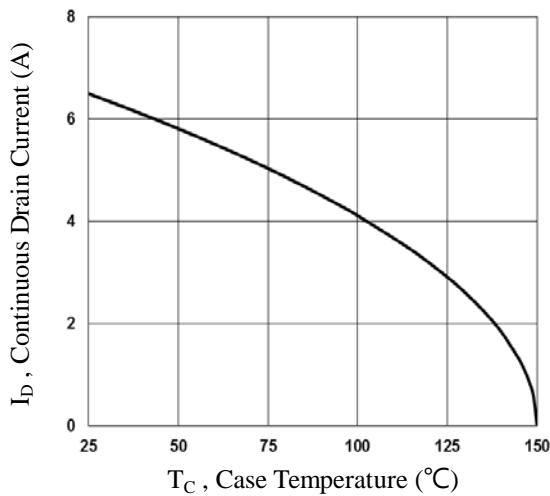
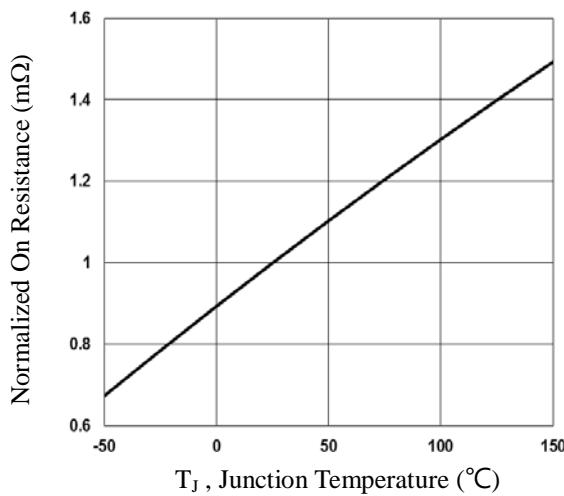
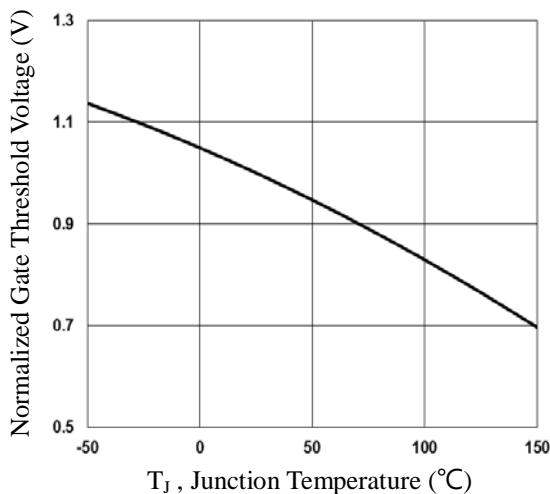
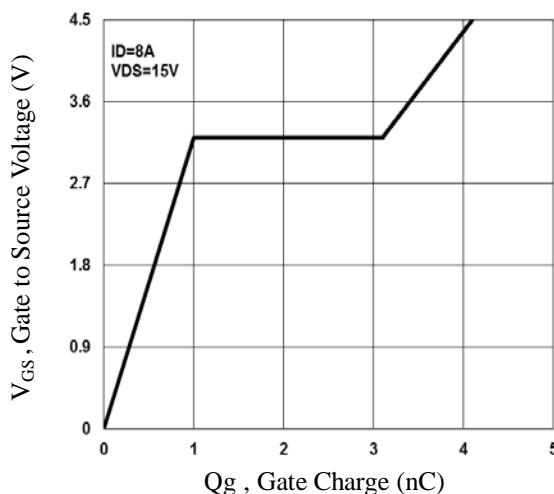
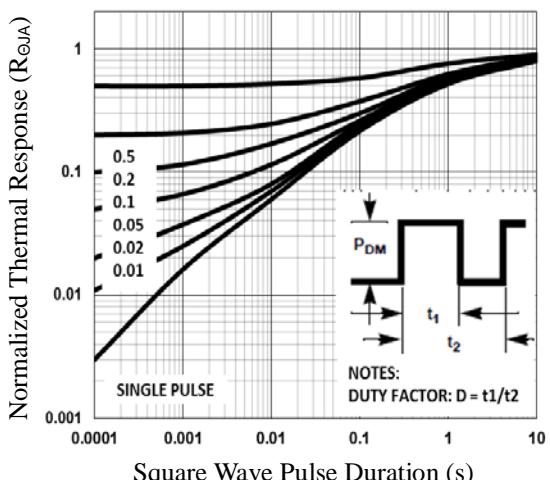
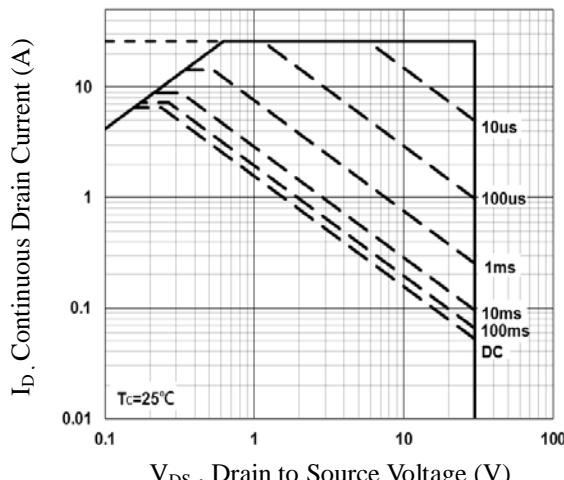
Q_g	Total Gate Charge ^{3,4}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=6\text{A}$	---	4.1	8	nC
Q_{gs}	Gate-Source Charge ^{3,4}		---	1	2	
Q_{gd}	Gate-Drain Charge ^{3,4}		---	2.1	4	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time ^{3,4}	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	2.8	5	ns
T_r	Rise Time ^{3,4}		---	7.2	14	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time ^{3,4}		---	15.8	30	
T_f	Fall Time ^{3,4}		---	4.6	9	
C_{iss}	Input Capacitance		---	345	500	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	55	80	
C_{rss}	Reverse Transfer Capacitance		---	32	45	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	3.2	6.4	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	6.5	A
			---	---	26	A
V_{SD}	Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
			---	---	---	ns
Q_{rr}	Reverse Recovery Charge	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $\text{di/dt}=100\text{A}/\mu\text{s}$ $T_J=25^\circ\text{C}$	---	---	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=1\text{mH}$, $I_{\text{AS}}=8\text{A}$, $R_g=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized RDS_{ON} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area

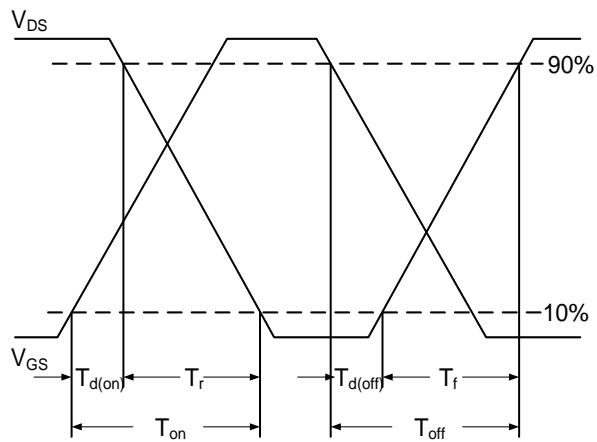


Fig.7 Switching Time Waveform

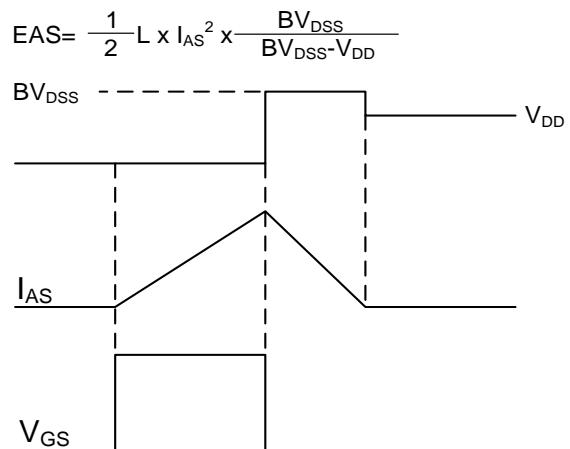
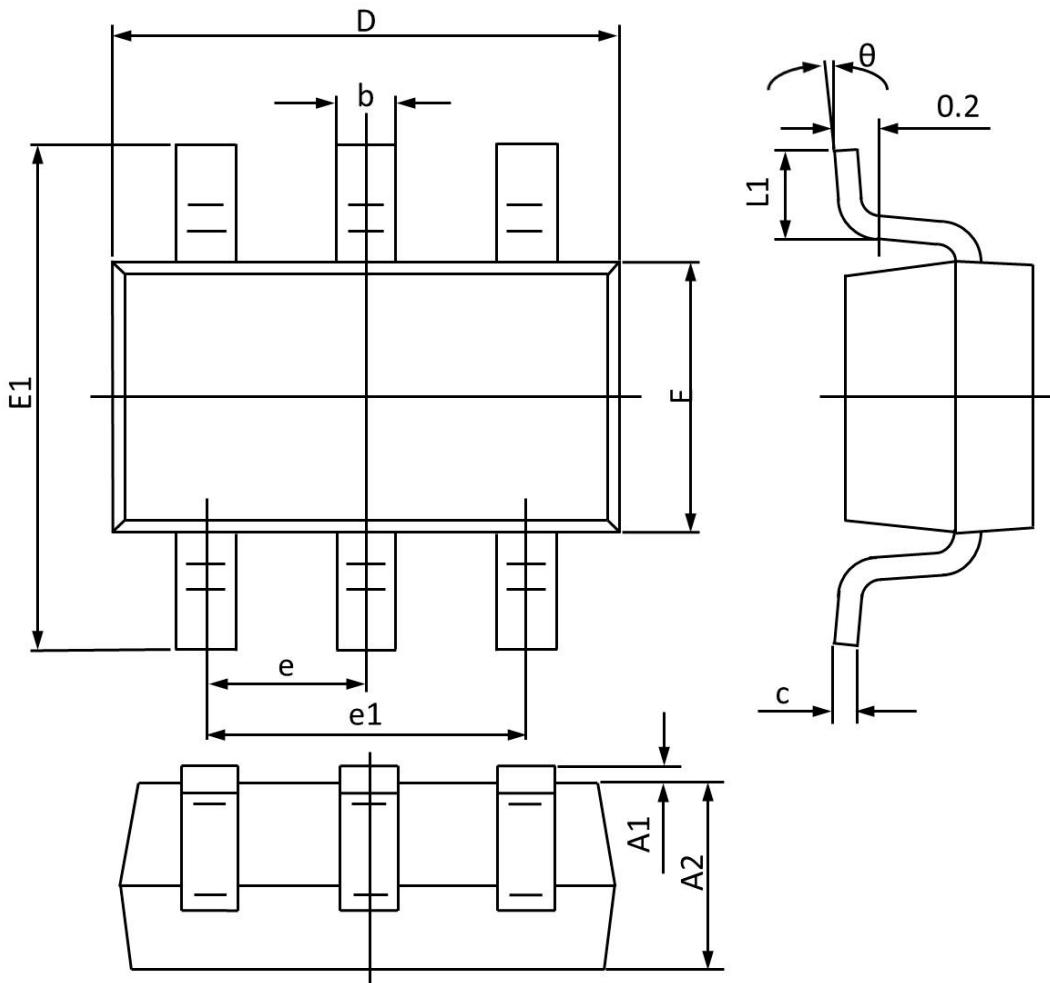


Fig.8 EAS Waveform

SOT23-6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.040	0.047
b	0.300	0.500	0.012	0.019
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E1	2.600	3.000	0.103	0.118
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.550	0.010	0.021
θ	0°	8°	0°	8°